



PD3S160

#### 1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER POWERDI®323

#### **Features**

- Guard Ring Die Construction for Transient Protection
- High Surge Capability
- Ultra-Small Surface Mount Package
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: POWERDI323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: Cathode Band
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.006 grams (approximate)

#### POWERDI323





Top View

**Bottom View** 

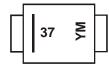
### **Ordering Information** (Note 4)

Part Number	Case	Packaging
PD3S160-7	POWERDI323	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**



37 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: T = 2006)M = Month (ex: 9 = September)

#### Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	Т	U	V	W	Х	Υ	Z	Α	В	С	D	Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	60	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	42	V
Average Forward Current (See also figure 4)	I <sub>F(AV)</sub>	1.0	Α
Repetitive Peak Forward Current $t_p \le 1 \text{ms}$ ; $\delta \le 0.25$	IFRM	8	Α
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	22	Α

### **Thermal Characteristics**

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering Point	$R_{ heta JS}$	_	6	°C/W
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{ heta JA}$	173	_	°C/W
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ heta JA}$	125	_	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150		°C

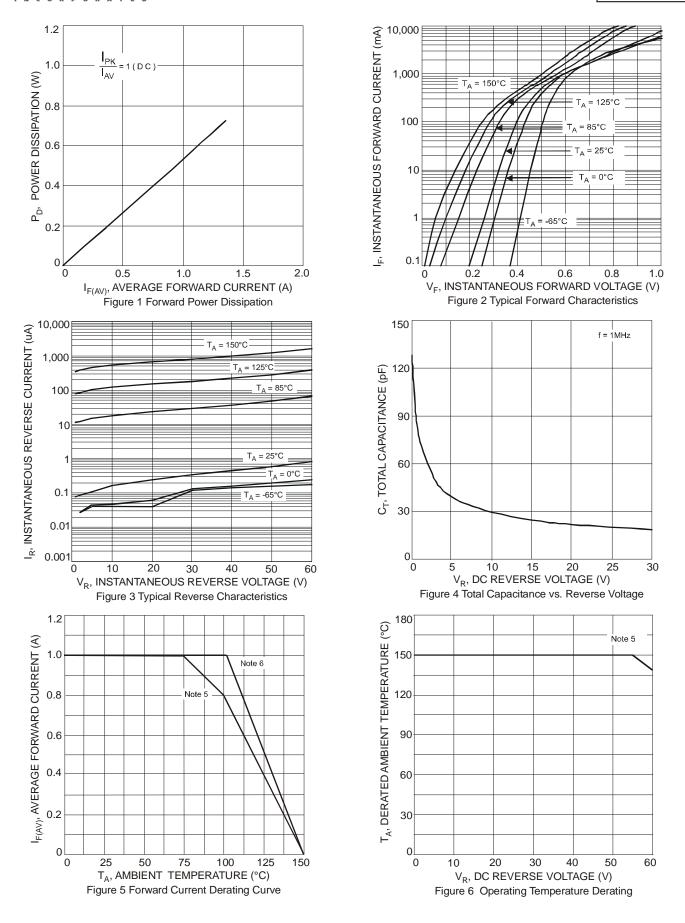
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	60	_	_	V	$I_R = 100 \mu A$
			0.40	0.45	V	I <sub>F</sub> = 0.1A
Forward Voltage	V <sub>F</sub>	_	0.55	0.58		$I_F = 0.7A$
				0.64		$I_F = 1.0A$
Leakage Current (Note 4)	-		0.3	5		$V_R = 5V, T_A = +25^{\circ}C$
Leakage Current (Note 4)	IR	_	3	50	μΑ	$V_R = 5V, T_A = +25^{\circ}C$ $V_R = 60V, T_A = +25^{\circ}C$
Total Capacitance (See also figure 3)	C <sub>T</sub>		38	_	рF	$V_R = 10V, f = 1.0MHz$

Notes:

- 5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.  $T_A$  = +25°C. 6. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com.  $T_A$  = +25°C. 7. Short duration pulse test used to minimize self-heating effect.

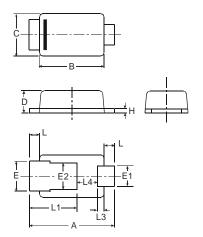






# **Package Outline Dimensions**

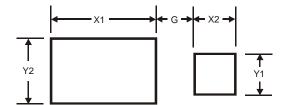
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI323						
Dim	Min	Max	Тур			
Α	2.40	2.60	2.50			
В	1.85	1.95	1.90			
С	1.20	1.30	1.25			
D	0.60	0.70	0.65			
Е	0.78	0.98	0.88			
E1	0.50	0.70	0.60			
E2	0.60	1.00	0.80			
Н	0.08	0.18	0.13			
L	0.20	0.40	0.30			
L1	_	_	1.40			
L3	_		0.20			
L4	0.40	0.80	0.60			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.5
X1	2.0
X2	0.8
Y1	0.8
Y2	1.1



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